

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|----------------|--|-----------------|------------------|-------------------------|------------------|
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.71788 | 100.0 | 7.7 |
| | | | Subtotal | 0.71788 | 100 | 7.7 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.03739 | 0.1 | 0.401 |
| | Copper alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.01122 | 0.03 | 0.1203 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.03739 | 0.1 | 0.401 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 37.29984 | 99.77 | 400.0777 |
| | | | Subtotal | 37.38584 | 100 | 401 |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 2.83275 | 4.8 | 30.384 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 5.90155 | 10.0 | 63.3 |
| | Filler | Silica fused | 60676-86-0 | 50.1632 | 85.0 | 538.05 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.11803 | 0.2 | 1.266 |
| | | | Subtotal | 59.01553 | 100 | 633 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 2.33079 | 100.0 | 25 |
| | | | Subtotal | 2.33079 | 100 | 25 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.0139 | 100.0 | 0.1491 |
| | Pure metal | Aluminium (Al) | 7429-90-5 | 0.20977 | 100.0 | 2.25 |
| | | | Subtotal | 0.22367 | 200 | 2.3991 |
| Die Attach | Lead alloy | Tin (Sn) | 7440-31-5 | 0.00653 | 2.0 | 0.07 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.00816 | 2.5 | 0.0875 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.31163 | 95.5 | 3.3425 |
| | | | Subtotal | 0.32632 | 100 | 3.5 |
| | | | Total | 100.00003 | 100 | 1072.5991 |

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